

## EE 330 Fall 2012

### Homework 6

**Due Friday September 28 at the beginning of the lecture. You MUST clearly indicate your name and SECTION on the first page of your HW. Submissions that do not include the section WILL NOT be graded.**

If parameters are needed for process characterization beyond what is specified in a problem, use the measured parameters from the AMI 0.5 $\mu$  (now ON) or the IBM 0.13 $\mu$  process runs that are attached.

#### Problem 1 (10 points):

Size an n-channel transistor in the AMI 0.5 $\mu$  CMOS process so that the impedance in the switch-level model is 1000 $\Omega$  when operating with a 3.5V power supply. Repeat for an n-channel transistor in the IBM 0.13 $\mu$  CMOS process when operating with a 1.5V supply.

#### Problem 2 (5 points):

If a minimum-sized inverter designed in the IBM 0.13 $\mu$  CMOS process could directly drive a minimum-sized inverter designed in the AMI 0.5 $\mu$  CMOS process, what would be  $t_{HL}$  and  $t_{LH}$ ? Assume a supply voltage of 1.5V. Neglect any interconnect parasitics.

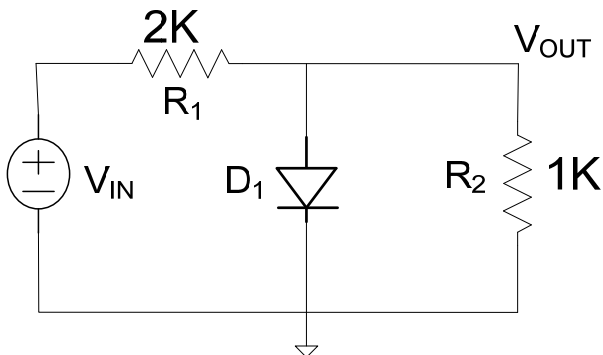
#### Problem 3 (5 points):

Using the short-channel  $\alpha$ -law model, determine the impedance in the switch-level model of the MOSFET for a square ( $W=L$ ) n-channel device if the short-channel device has the same  $\mu C_{OX}$  and  $V_T$  as in the IBM 0.13 $\mu$  process but with short-channel parameters  $\theta_1=\theta_2=1/2$  and  $\alpha=1.25$ . Comment on how the short-channel effect changes the switching performance of the MOSFET.

#### Problem 4 (10 points):

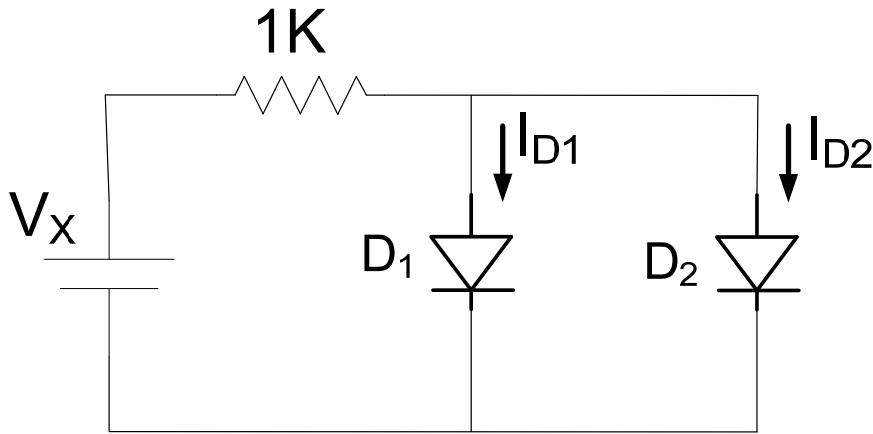
Consider the below circuit

- Obtain the voltage  $V_{OUT}$  if  $V_{IN}=-8V$ .
- Obtain the current through  $R_2$  if  $V_{IN}=5V$
- Obtain an expression for  $V_{OUT}$  and plot it for one period of the input is  $V_{IN} = 5\sin 1000t$

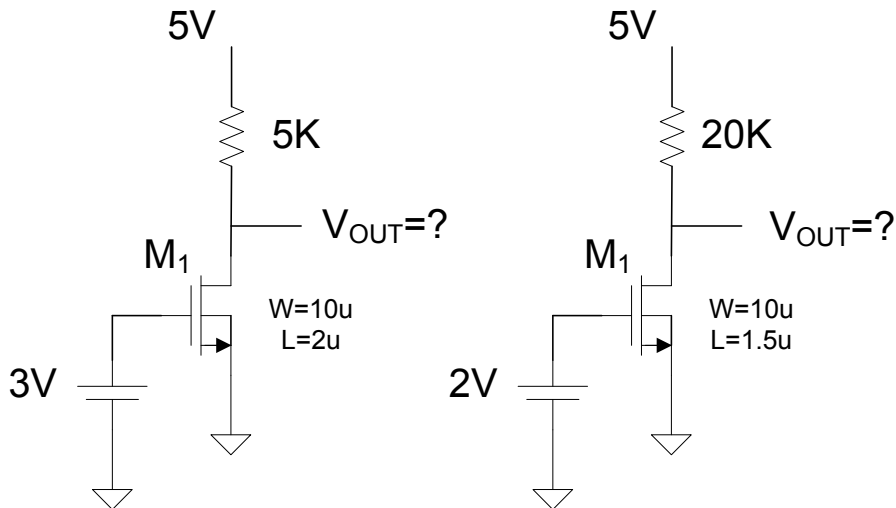


**Problem 5 (10 points):**

Assume the junction area of  $D_1$  is  $100\mu^2$  and that of  $D_2$  is 4 times as large. Determine the current  $I_{D1}$  if  $V_X=1.5V$ . Assume  $J_S$  to be  $5fA/\mu^2$ .

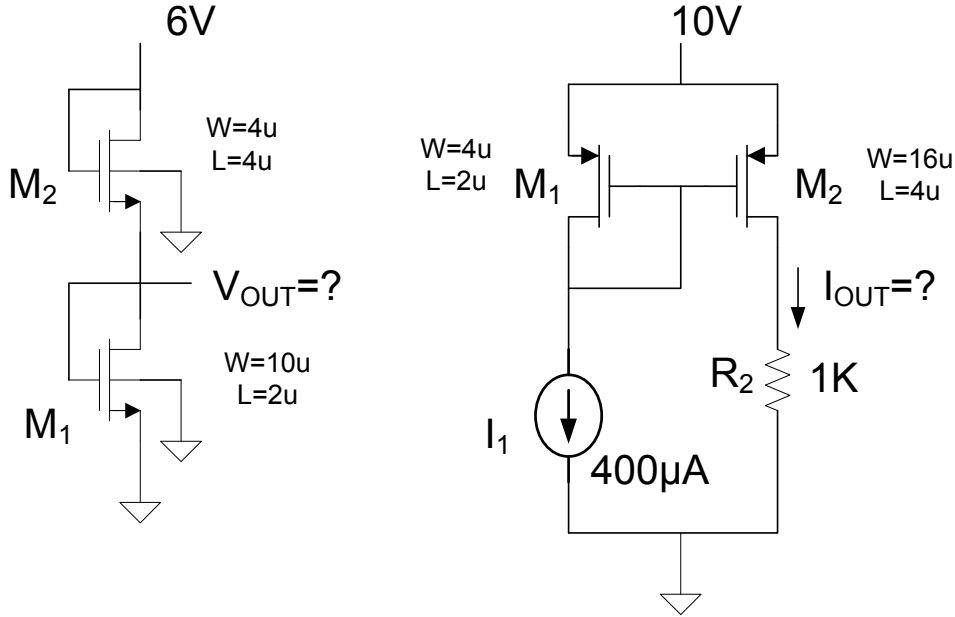
**Problem 6 (10 points):**

Analytically determine the variable indicated by a “?” in the below circuits. Assume the devices are in a process with  $V_{TN}=1V$ , and  $\mu_n C_{OX}=100\mu A/V^2$



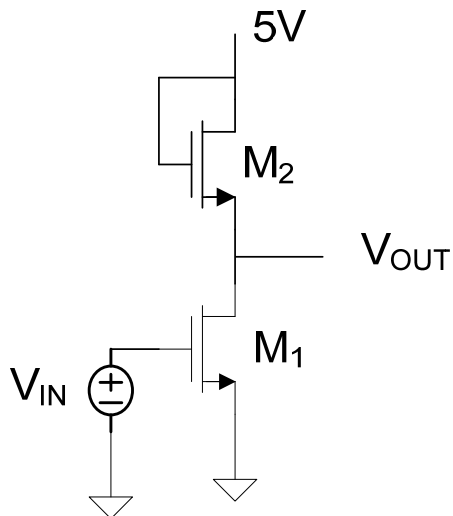
**Problem 7 (10 points):**

Analytically determine the variable indicated by a “?” in the below circuits. Assume the devices are in a process with  $V_{TN}=1V$ ,  $V_{TP}=-1V$ ,  $\mu_n C_{OX}=100\mu AV^{-2}$  and  $\mu_p C_{OX}=33\mu AV^{-2}$ .

**Problem 8 (15 points):**

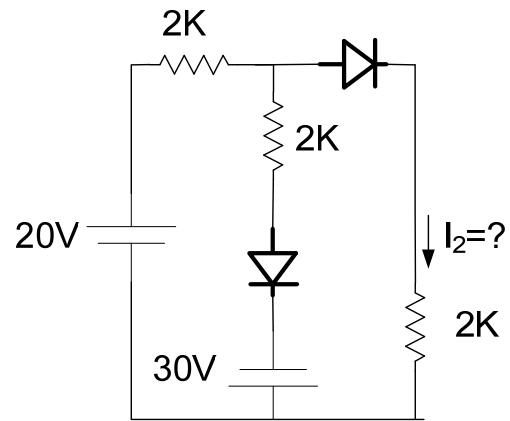
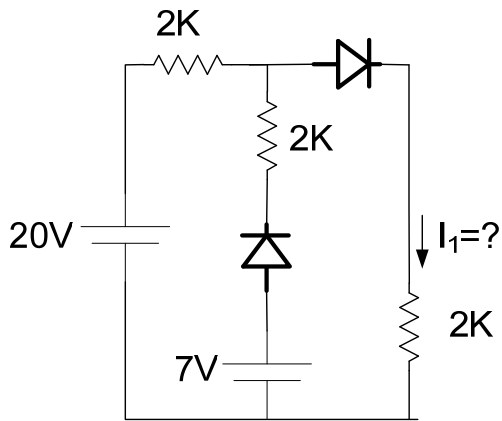
Consider the below circuit.

- If  $V_{IN}=3V$ , determine the dimensions of  $M_1$  that will result in an output voltage of 2V. Assume that the dimensions of  $M_2$  are  $W_2=10u$  and  $L_2=1u$ . The model parameters of the devices are  $V_{TN}=1V$ ,  $V_{TP}=-1V$ ,  $\mu_n C_{OX}=100\mu AV^{-2}$  and  $\mu_p C_{OX}=33\mu AV^{-2}$ .
- Repeat part a) if the goal is to have an output voltage of 0.5V.

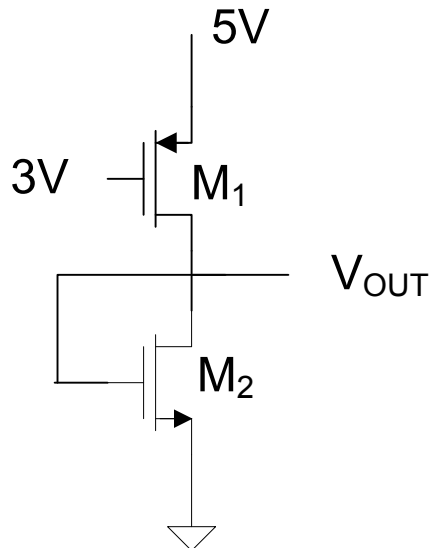


**Problem 9 (10 points):**

Determine the currents indicated with a “?” in the below circuits. Assume the diodes are ideal.

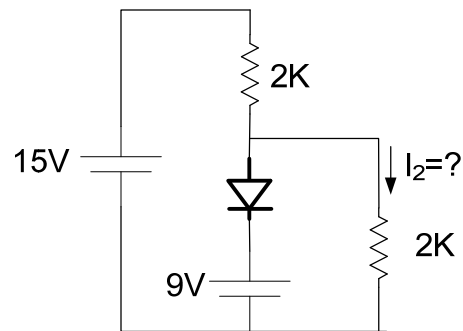
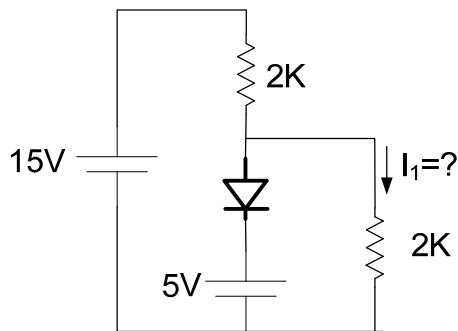
**Problem 10 (10 points):**

Determine  $V_{OUT}$  for the below circuit. Assume the devices  $M_1$  and  $M_2$  are identically sized with  $W=L=5\mu$ . The model parameters of the devices are  $V_{TN}=1V$ ,  $V_{TP}=-1V$ ,  $\mu_n C_{OX}=100\mu A/V^2$  and  $\mu_p C_{OX}=33\mu A/V^2$ .



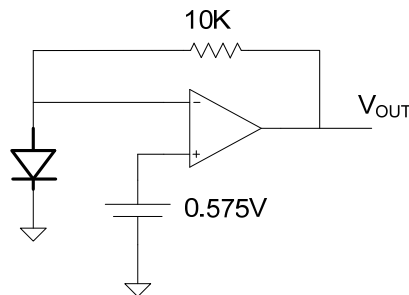
**Problem 11 (Extra Credit of 10 points):**

Determine the currents indicated with a “?” in the below circuits. Assume the diodes are ideal.

**Problem 12 (Extra Credit of 10 points):**

Assume the op amp is ideal and biased with  $V_{DD}=20V$  and  $V_{SS}=-20V$  and the diode is characterized by model parameters:  $J_{SX}=0.5A/\mu^2$ ,  $V_{G0}=1.17V$ ,  $m=2.3$ . Assume the area of the junction is  $100\mu^2$ .

- Determine  $V_{OUT}$  if  $T = -20^\circ C$
- Repeat part a) if  $T = 40^\circ C$ .
- Repeat part a) if  $T = 120^\circ C$

**Problem 13 (Extra Credit of 20 points):**

Using Verilog, build a counter that outputs to a seven segment display. Whenever the INPUT makes a low to high transition, the counter should increase by one. This should be reflected by the seven segment display. Each bit of the seven segment display is controlled by an individual output. A high output corresponds to a lit segment while a low output causes an unlit segment. The counter should go back to zero upon passing 9. Label your outputs clearly and prove your design with sufficient testing.

# MOSIS WAFER ACCEPTANCE TESTS

RUN: T86S  
TECHNOLOGY: SCN05

VENDOR: AMIS  
FEATURE SIZE: 0.5 microns

Run type: SKD

INTRODUCTION: This report contains the lot average results obtained by MOSIS from measurements of MOSIS test structures on each wafer of this fabrication lot. SPICE parameters obtained from similar measurements on a selected wafer are also attached.

COMMENTS: American Microsystems, Inc. C5

TRANSISTOR PARAMETERS	W/L	N-CHANNEL	P-CHANNEL	UNITS
MINIMUM	3.0/0.6			
Vth		0.79	-0.92	volts
SHORT	20.0/0.6			
Idss		463	-248	uA/um
Vth		0.67	-0.91	volts
Vpt		10.0	-10.0	volts
WIDE	20.0/0.6			
Ids0		< 2.5	< 2.5	pA/um
LARGE	50/50			
Vth		0.68	-0.95	volts
Vjbkd		10.8	-11.7	volts
Ijlk		<50.0	<50.0	pA
Gamma		0.49	0.57	V^0.5
K' (Uo*Cox/2)		57.8	-19.1	uA/V^2
Low-field Mobility		475.38	157.09	cm^2/V*s

COMMENTS: Poly bias varies with design technology. To account for mask bias use the appropriate value for the parameter XL in your SPICE model card.

Design Technology	XL (um)	XW (um)
SCMOS_SUBM (lambda=0.30)	0.10	0.00
SCMOS (lambda=0.35)	0.00	0.20

FOX TRANSISTORS	GATE	N+ACTIVE	P+ACTIVE	UNITS
Vth	Poly	>15.0	<-15.0	volts

AMI 0.5u Process Description  
Continued

PROCESS PARAMETERS	N+	P+	POLY	PLY2_HR	POLY2	M1	M2	UNITS
Sheet Resistance	84.4	109.2	22.9	1102	41.9	0.09	0.09	ohms/sq
Contact Resistance	60.9	150.6	15.8		26.8		0.81	ohms
Gate Oxide Thickness	142							angstrom

PROCESS PARAMETERS	M3	N\PLY	N_W	UNITS
Sheet Resistance	0.05	818	808	ohms/sq
Contact Resistance	0.81			ohms

COMMENTS: N\POLY is N-well under polysilicon.

CAPACITANCE PARAMETERS	N+	P+	POLY	POLY2	M1	M2	M3	N_W	UNITS
Area (substrate)	426	724	85		30	15	9	37	aF/um^2
Area (N+active)			2434		34	17	12		aF/um^2
Area (P+active)			2351						aF/um^2
Area (poly)				899	56	16	9		aF/um^2
Area (poly2)					46				aF/um^2
Area (metal1)						33	13		aF/um^2
Area (metal2)							32		aF/um^2
Fringe (substrate)	361	241			71	49	33		aF/um
Fringe (poly)					59	38	28		aF/um
Fringe (metal1)						46	34		aF/um
Fringe (metal2)							54		aF/um
Overlap (N+active)			292						aF/um
Overlap (P+active)			387						aF/um

CIRCUIT PARAMETERS		UNITS
Inverters	K	
Vinv	1.0	2.04 volts
Vinv	1.5	2.29 volts
Vol (100 uA)	2.0	0.12 volts
Voh (100 uA)	2.0	4.86 volts
Vinv	2.0	2.47 volts
Gain	2.0	-18.26
Ring Oscillator Freq.		
DIV256 (31-stg,5.0V)	98.75	MHz
D256_WIDE (31-stg,5.0V)	153.47	MHz
Ring Oscillator Power		
DIV256 (31-stg,5.0V)	0.49	uW/MHz/gate
D256_WIDE (31-stg,5.0V)	1.00	uW/MHz/gate

COMMENTS: SUBMICRON

# MOSIS WAFER ACCEPTANCE TESTS

RUN: T85X (8WL\_8LM\_OL)  
TECHNOLOGY: SIGE013

VENDOR: IBM-BURLINGTON  
FEATURE SIZE: 0.13 microns

Run type: SKD

INTRODUCTION: This report contains the lot average results obtained by MOSIS from measurements of MOSIS test structures on each wafer of this fabrication lot. SPICE parameters obtained from similar measurements on a selected wafer are also attached.

COMMENTS: SIGE8WL\_IBM-BU

TRANSISTOR PARAMETERS	W/L	N-CHANNEL	P-CHANNEL	UNITS
MINIMUM	0.16/0.12			
Vth		0.41	-0.42	volts
SHORT	20.0/0.12			
Idss		406	-178	uA/um
Vth		0.43	-0.42	volts
Vpt		3.6	-3.6	volts
WIDE	20.0/0.12			
Ids0		155.2	-127.9	pA/um
LARGE	20.0/20.0			
Vth		0.12	-0.23	volts
Vjblk		2.7	-3.2	volts
Ijlk		<50.0	<50.0	pA
Gamma		0.28	0.23	V^0.5
K' (Uo*Cox/2)		308.0	-48.8	uA/V^2
Low-field Mobility		553.02	87.62	cm^2/V*s



# IBM 0.13u Process Description Continued

PROCESS PARAMETERS	N+	P+	POLY	M1	M2	M3	M4	UNITS
Sheet Resistance	6.7	6.3	6.6					ohms/sq
Sheet Resistance				78	51	50	50	mohms/sq
Contact Resistance	9.4	9.2	8.3		0.68	1.37	2.00	ohms
Gate Oxide Thickness	31							angstrom

PROCESS PARAMETERS	M5	M6	M7	M8	N_W	PPLY+BLK	N+BLK	POLY_NON	POLY_NON	TaN	UNITS
Sheet Resistance	41	44	7	7.4							mohms/sq
Sheet Resistance					327	321.2	73.4	231.6	1547.4	58.9	ohms/sq
Contact Resistance	2.19	2.51	2.51	2.53							ohms

COMMENTS: BLK is silicide block.

CAPACITANCE PARAMETERS	N+	P+	POLY	M1	M2	M3	M4	M5	M6	M7	M8	TaN	MiM	UNITS
Area (substrate)	973	1203	109	57	41	32	27	23	20	17	14	24		aF/um^2
Area (N+active)			11176											aF/um^2
Area (P+active)			10496											aF/um^2
Area (r well)	605													aF/um^2
Area (N+ HA varactor)		2390												aF/um^2
Area (M1)			128											aF/um^2
Area (M2)				171										aF/um^2
Area (M3)					182									aF/um^2
Area (M4)						176								aF/um^2
Area (M5)							82							aF/um^2
Area (M6)								81						aF/um^2
Area (M7)									45					aF/um^2
Area (M8)										85				aF/um^2
Area (MiM)												4100		aF/um^2
Fringe (substrate)	60	68												aF/um

CIRCUIT PARAMETERS			UNITS
Inverters	K		
Vinv	1.0	0.50	volts
Vinv	1.5	0.52	volts
Vol (100 uA)	2.0	0.01	volts
Voh (100 uA)	2.0	1.18	volts
Vinv	2.0	0.53	volts
Gain	2.0	-18.48	
Ring Oscillator Freq.			
DIV1024 (31-stg,1.2V)		376.81	MHz
D1024_THK (31-stg,2.5V)		279.93	MHz
Ring Oscillator Power			
DIV1024 (31-stg,1.2V)		5.13	nW/MHz/gate
D1024_THK (31-stg,2.5V)		26.50	nW/MHz/gate
Operational Amplifier			
Gain		10	

COMMENTS: DEEP\_SUBMICRON